반도체 package 용 Moisture barrier bag 의 기계적 물성 연구

(Mechanical tenacity analysis of moisture barrier bag for semiconductor package)

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Abstract

We have been using Moisture Barrier Bag for dry packing of semiconductor package to prevent moisture from absorbing during shipping. Moisture barrier bag material is required to be water proof, vapor proof and offer superior ESD(Electro-static discharge) shielding and EMI shielding. Also, the bag should be formed easily to the shape of products for vacuum packing while providing excellent puncture resistance and offer very low gas, moisture permeation. There are some problems like pin hole after sealing and punctured bag before surface mount process. It should be developed to meet the requirements of excellent electrical property and physical property by means of optimization of used material composition and its thickness in moisture barrier bag. This study investigates on characterization of moisture barrier bag material in terms of mechanical endurance testing, tensile strength and thermal analysis.